

FEED DEVICES AND METHODS
FOR INJECTION MOLDED SOLDER SYSTEMS

ABSTRACT OF THE DISCLOSURE

A solder feeding device having a reservoir, a drive unit, a first lead, and a second lead is provided. The reservoir melts solid solder wire into molten solder, while the drive unit selectively feeds the solid solder wire into the reservoir. The first and second leads are in electrical communication with the drive unit. The first lead is positioned in the reservoir so that it electrically communicates with the second lead through the molten solder when the molten solder reaches a triggering level, but so that it does not electrically communicate with the second lead when the level is below the triggering level. The drive unit feeds the solid solder wire into the reservoir based upon a state of electrical communication between the first and second leads.